# 전기 전자 | 반도체 분야 해석 엔지니어를 위한 Ansys Tech Summit

2024.6.4 10:00 – 17:00 | 수원컨벤션센터 4층

| Time | | Agenda | | | | |
|---|---|---|---|---|---|---|
| **Start** | **End** | **Keynote** | | | | |
| 10:00 | 10:20 | 환영사 - 박주일 대표 | | | | |
| 10:20 | 10:40 | Ansys New Technology Offering for High-Tech Industry - 강태신 전무 | | | | |
| 10:40 | 11:00 | Sim AI: Predict at the Speed of AI - 이정원 매니저 | | | | |
| 11:00 | 11:30 | Powering Innovation with Simulation- Sara Louie | | | | |
| 11:30 | 13:00 | **Lunch & Optics Tech Talk** | | | | |
| | | **Track 1**<br>**Electronics** | **Track 2**<br>**Mechanical & Fluid** | **Track 3**<br>**Optics \| New & Emerging Tech.** | **Track 4**<br>**Semiconductor** | **Track 5**<br>**3DIC & Interposer for HBM** |
| 13:00 | 13:30 | Best Known Methods: Modeling Package and PCB | Battery Solution in LS-DYNA | An Optical System Design Perspective on Comprehensive Silicon Photonics Solutions for CPO | Redhawk-SC Advanced feature. Hierarchical ROM, SigmaPD, SigmaAV | 3DIC Multiphysics solution overview |
| 13:30 | 14:00 | Automating PCB embedded Noise Filter Integration and PCB Ground Design Validation. | Ansys Mechanical Solutions for Semiconductor and Hitech Applications | AR VR System Design & Analysis Through Ansys Optical Solution | Diakopto IC design and layout parasitics analysis & debugging | 3DIC Thermal Reliability RHSC-ET |
| 14:00 | 14:30 | **Break & Ansys GPT Tech Talk** | | | | |
| 14:30 | 15:00 | Thermal Aware Floorplan Design Optimization Workflow for Mobile Device SoC(System on Chips using Icepak-optiSLang | Exploring the Applications of ANSYS Motion in High-Tech Industry | CMOS Image Sensor (CIS) workflow & New generation of CIS with Ansys Solutions | Case Study on Model-Based Safety Analysis Using medini Semiconductor | 3DIC Stress Reliability RHSC-ET |
| 15:00 | 15:30 | Fast tracking Simulations with Reduced Order Models using Ansys Twin Builder | Fluent Native GPU Solver Update | Introduction to sensor development workflow and development using AVx | Introduction to helic tool on-chip Electromagnetic solution | What's New in HFSS-IC |
| 15:30 | 16:00 | **Break & Motion Tech Talk** | | | | |
| 16:00 | 16:30 | Introduction to High-tech solution using Maxwell | Case Study on Heat Exchanger Analysis using Thermal Desktop | MBSE workflow for the thermal performance optimization of Power electronics | PowerArtist advanced feature update | HFSS-IC: Simulation for interposer-SI |
| 16:30 | 17:00 | Powering Innovation Beyond 5G | Efficient and scalable GPU-oriented SPH solver: a real application study using Rocky | Accelerating Product Development with MBSE using Ansys ModelCenter | PathFidner-SC / Totem-SC Next generation EMIR,ESD in Custom design | |